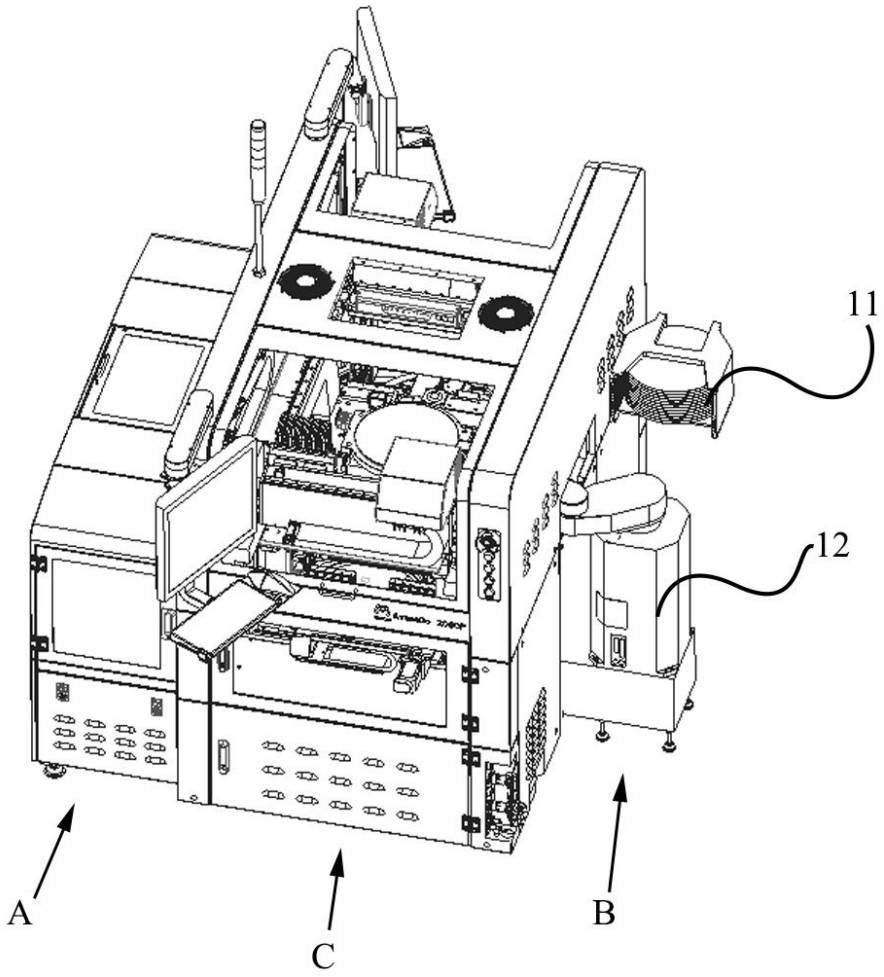

Figure 1

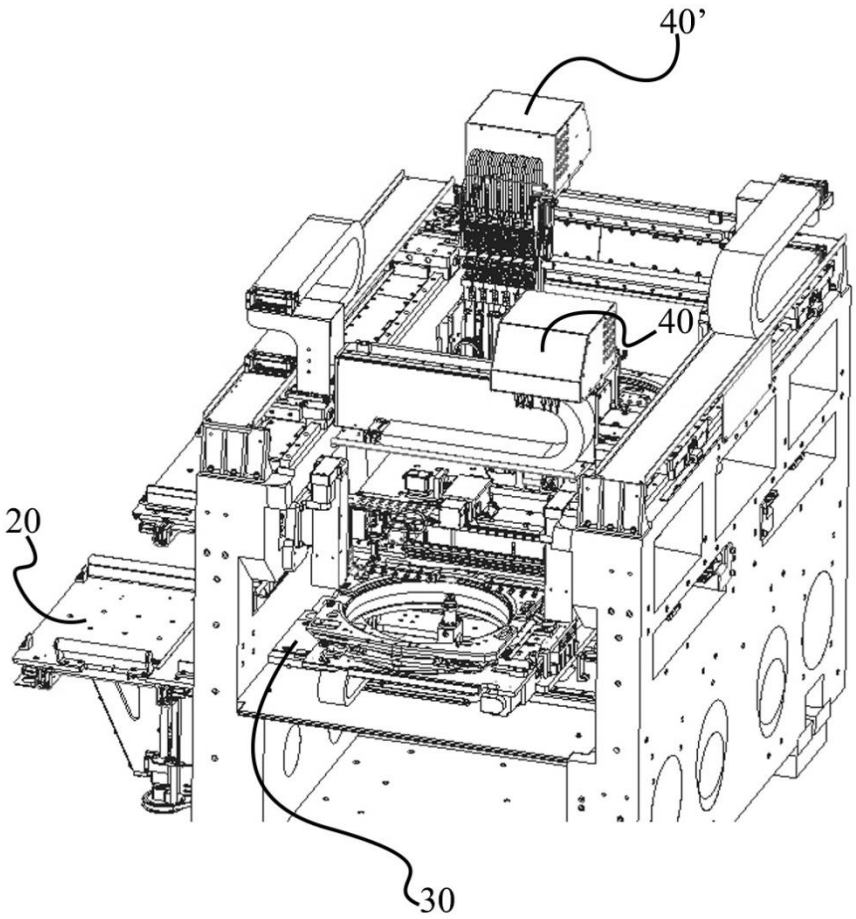

Figure 2

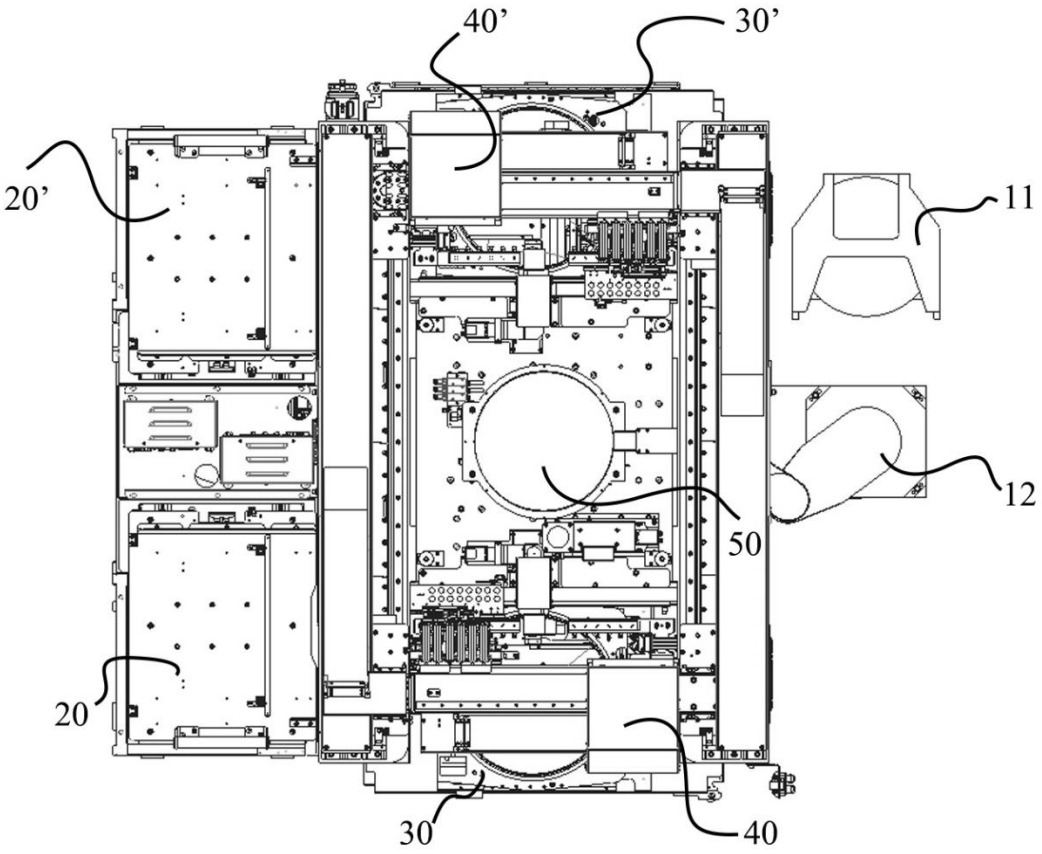

Figure 3

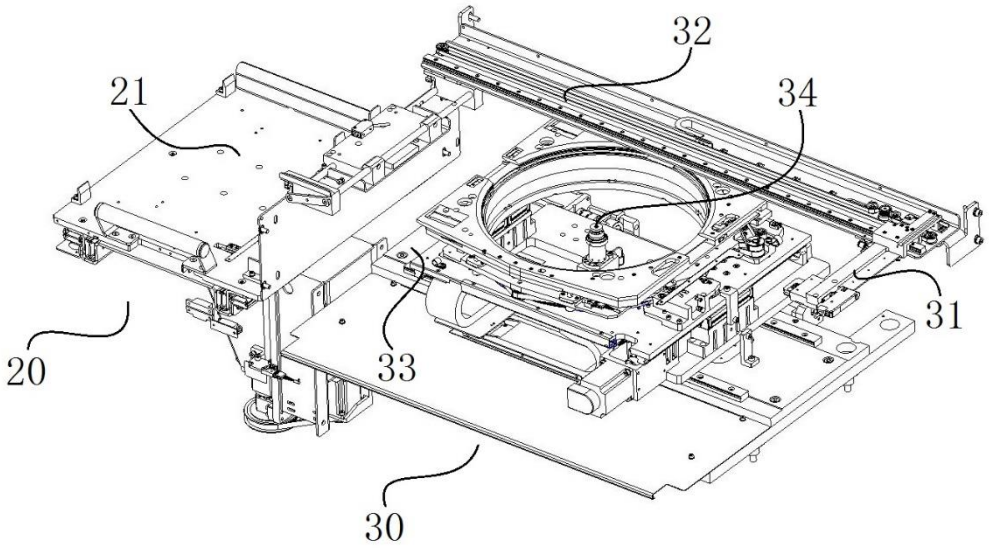

Figure 4

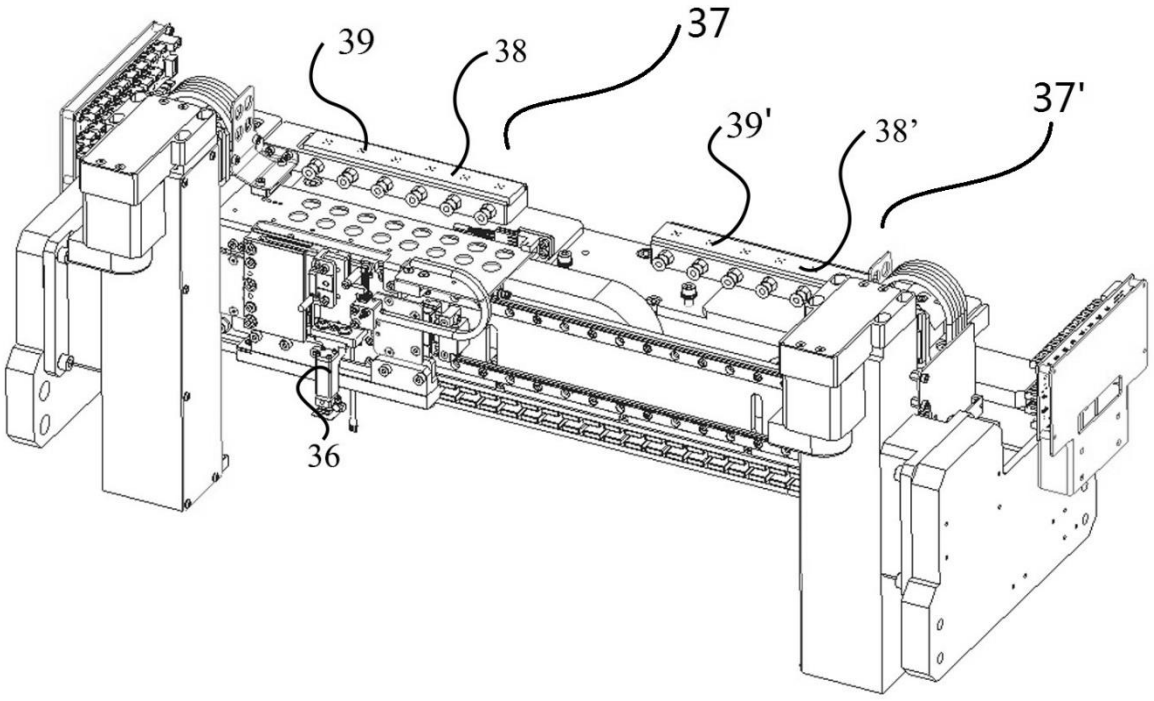

Figure 5

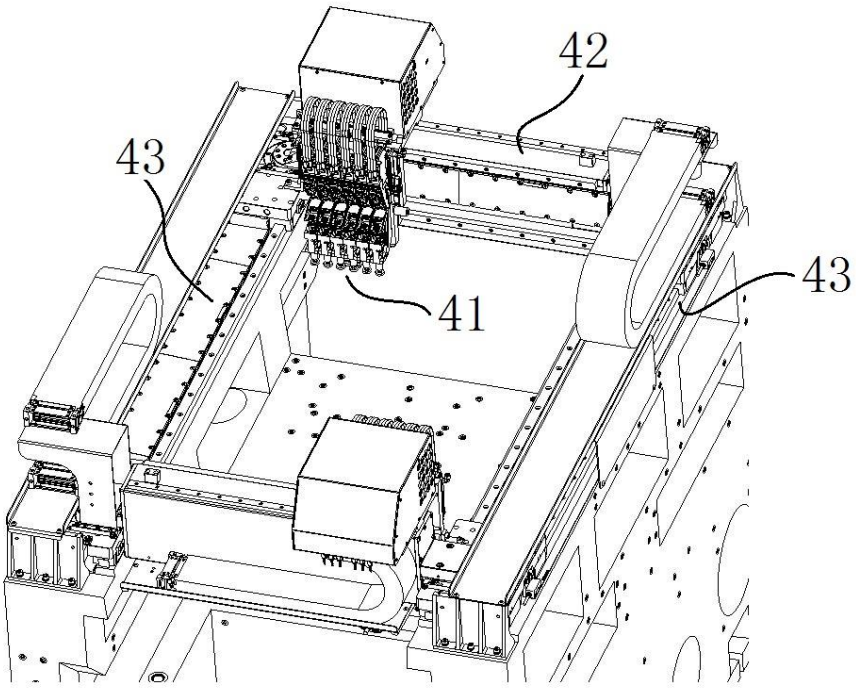

Figure 6

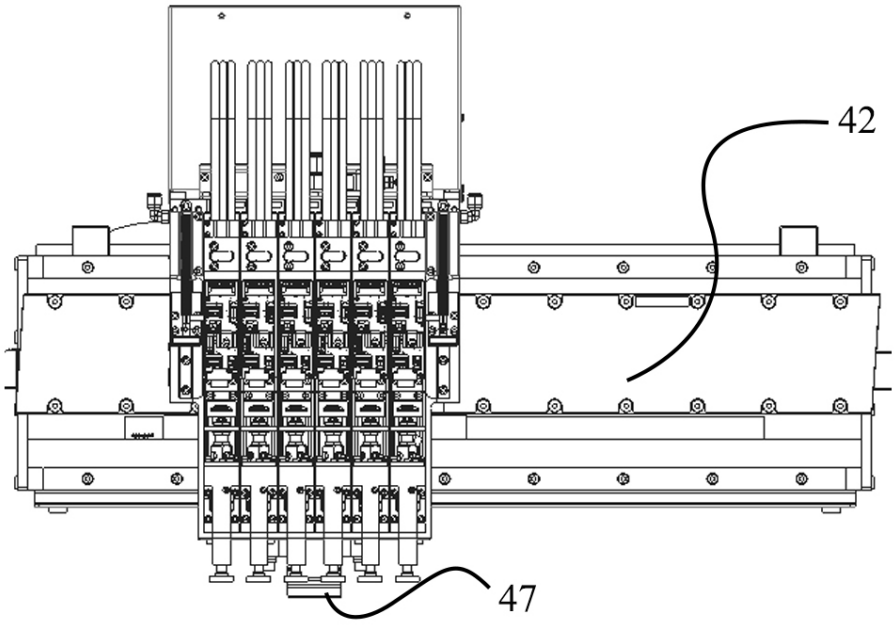

Figure 7

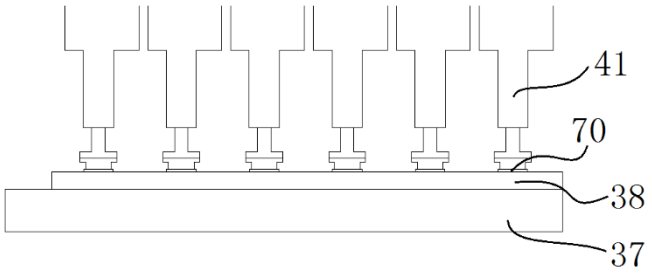

Figure 8

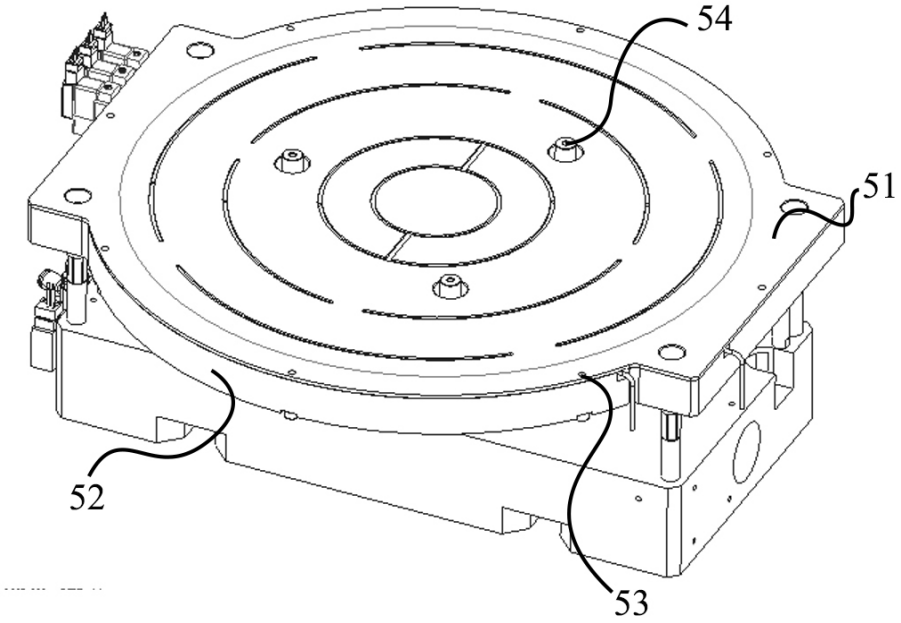

Figure 9

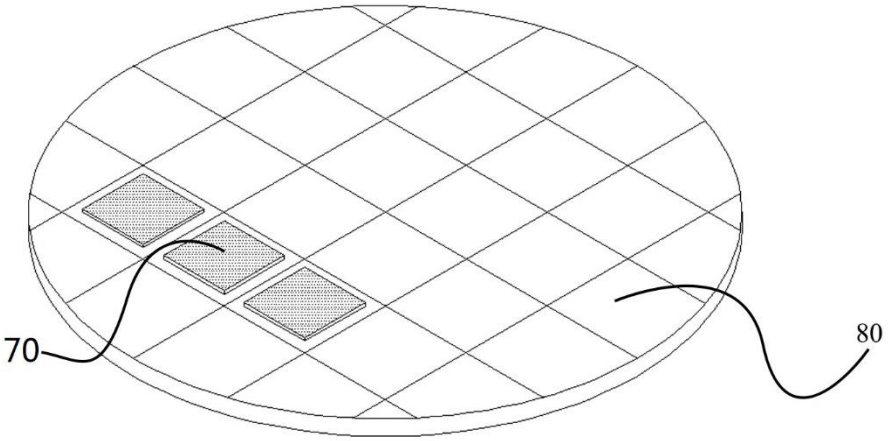

Figure 10A

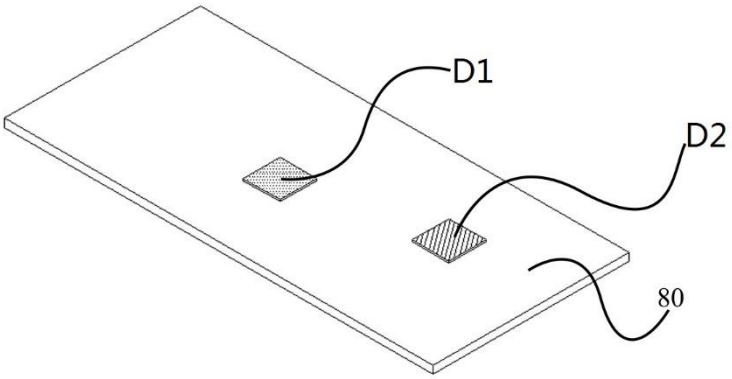

Figure 10B

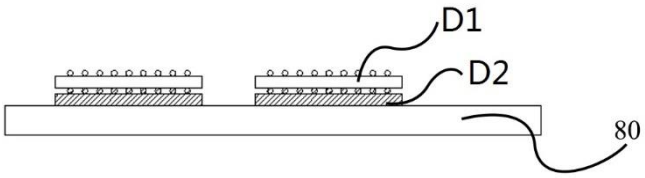

Figure 10C

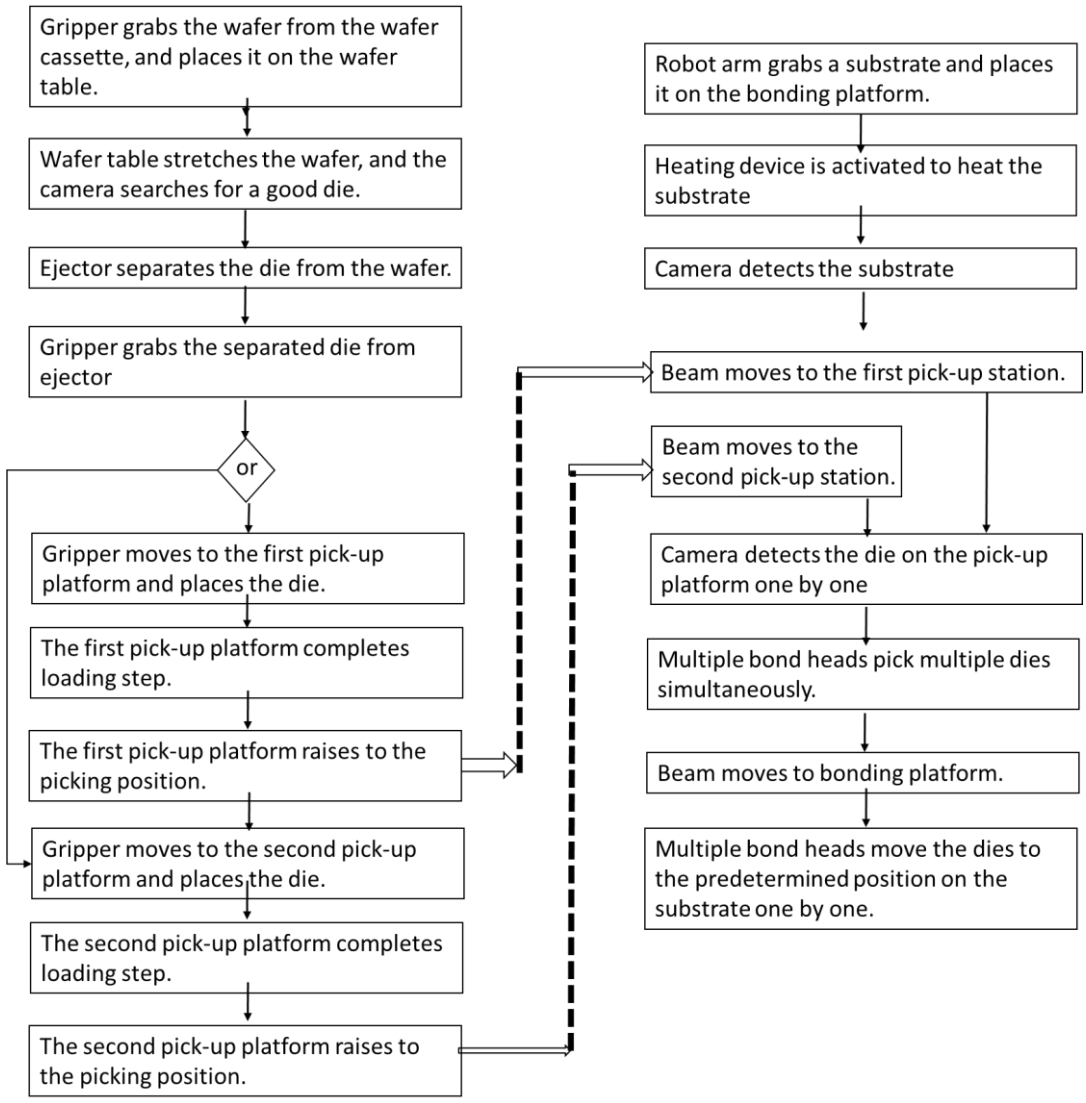
Gripper grabs the wafer from the wafer cassette, and places it on the wafer table.
Wafer table stretches the wafer, and the camera searches for a good die.
Ejector separates the die from the wafer.
Gripper grabs the separated die from ejector
or
Gripper moves to the first pick-up platform and places the die.
The first pick-up platform completes loading step.
The first pick-up platform raises to the picking position.
Gripper moves to the second pick-up platform and places the die.
The second pick-up platform completes loading step.
The second pick-up platform raises to the picking position.
Robot arm grabs a substrate and places it on the bonding platform.
Heating device is activated to heat the substrate
Camera detects the substrate
Beam moves to the first pick-up station.
Beam moves to the second pick-up station.
Camera detects the die on the pick-up platform one by one
Multiple bond heads pick multiple dies simultaneously.
Beam moves to bonding platform.
Multiple bond heads move the dies to the predetermined position on the substrate one by one.

Figure 11